SENSOR IC PACKAGE PORTFOLIO

SENSOR INTEGRATED CIRCUITS

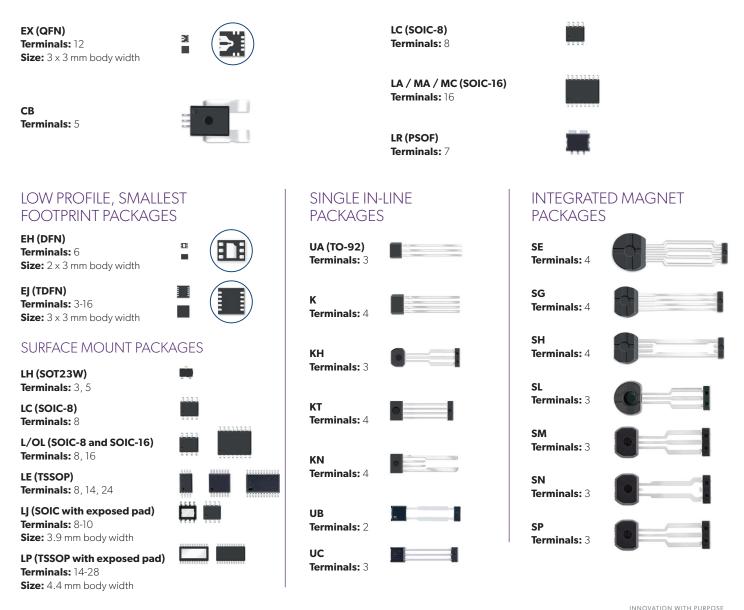
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The development of Allegro sensor ICs not only includes leading edge innovations in the area of integrated circuit design but also includes application specific innovation in the area of custom package design.

A small sampling of Allegro's custom packaging developments include:

- Proprietary, integrated magnet packages that simplify magnetic system design in automotive speed sensing applications.
- Custom SOICW packaging that offers ultra-low series resistance, higher power density, and improved isolation ratings in a tiny footprint. See the MC package.
- Revolutionary, integrated current sensing packages with high bandwidth magnetic design features. See the SOIC, QSOP, EX, and CA/CB packages with integrated, low resistance current conductors and the 1 mm thick KT package.
- Small footprint, low profile packages for communications and consumer products.

CURRENT SENSING PACKAGES WITH INTEGRATED CONDUCTORS





microsystems

ECI